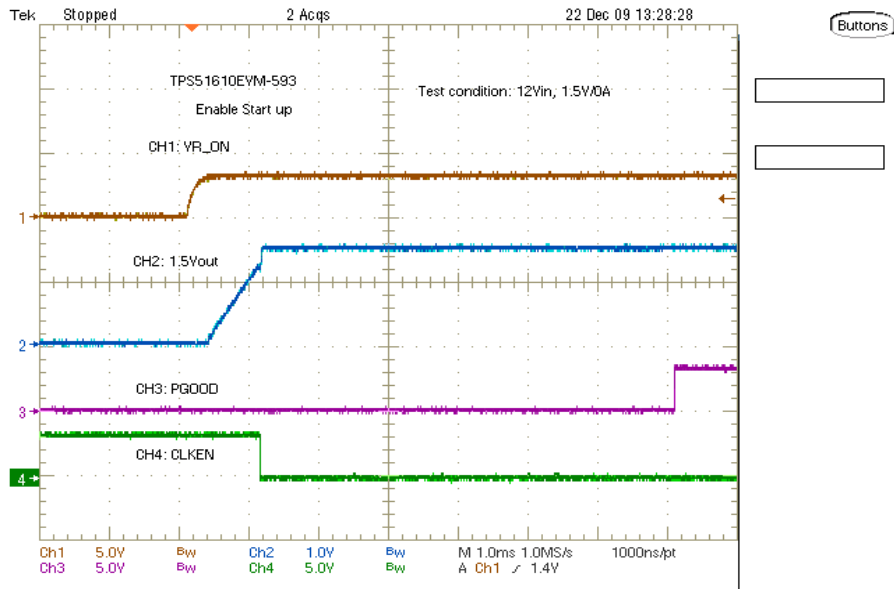
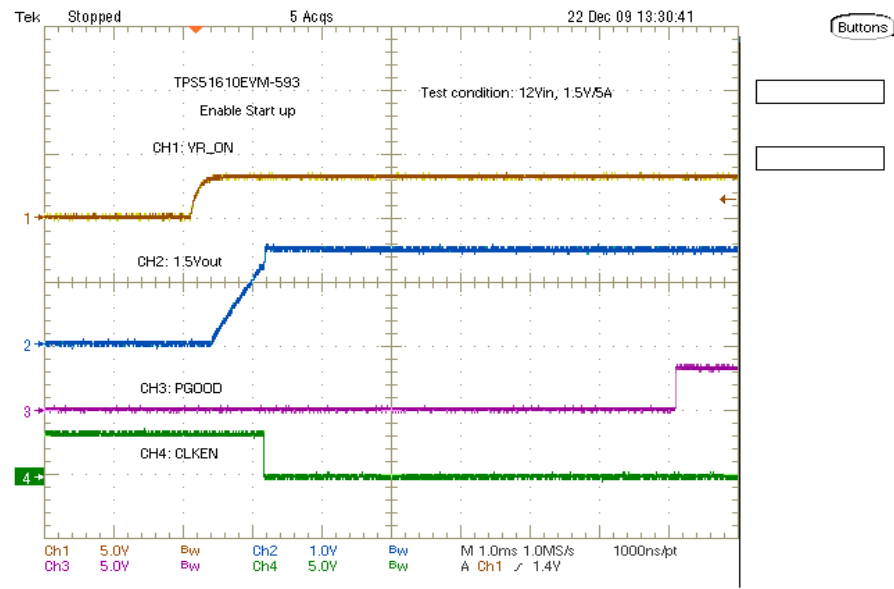


1. Enable Start Up

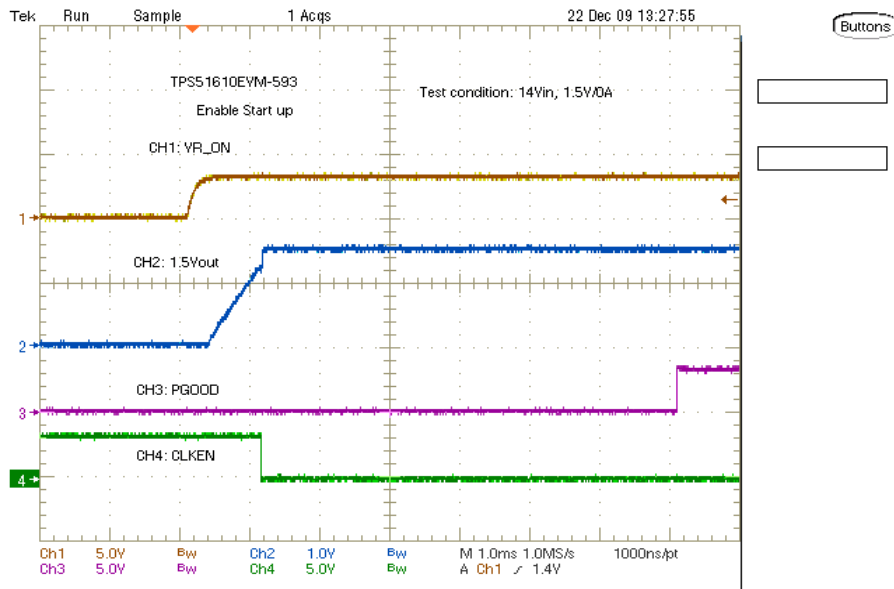
Test condition: 12Vin, 1.5V/0A



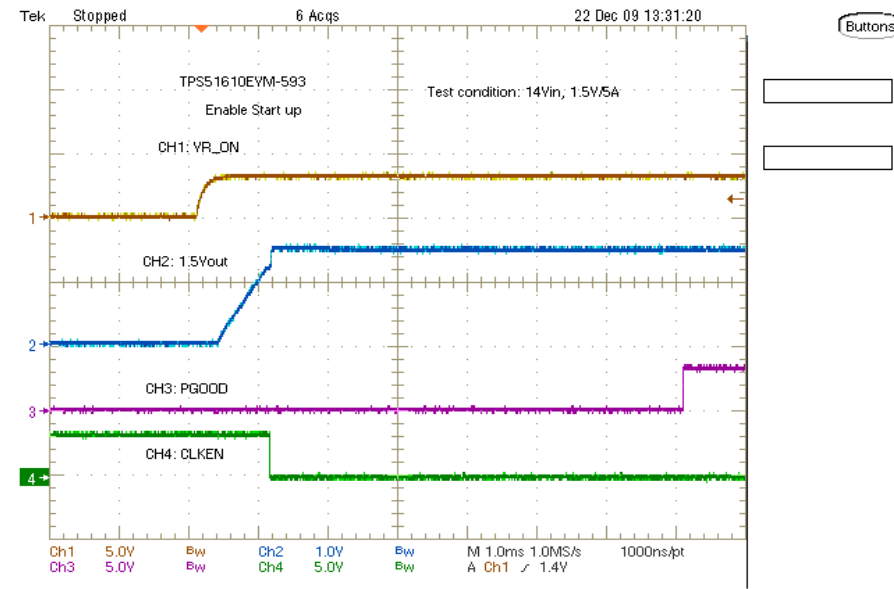
Test condition: 12Vin, 1.5V/5A



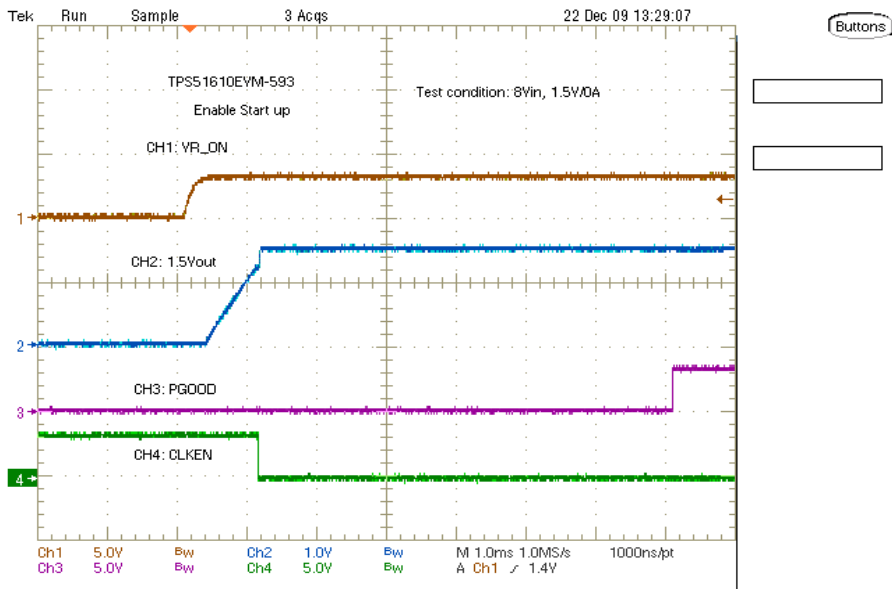
Test condition: 14Vin, 1.5V/0A



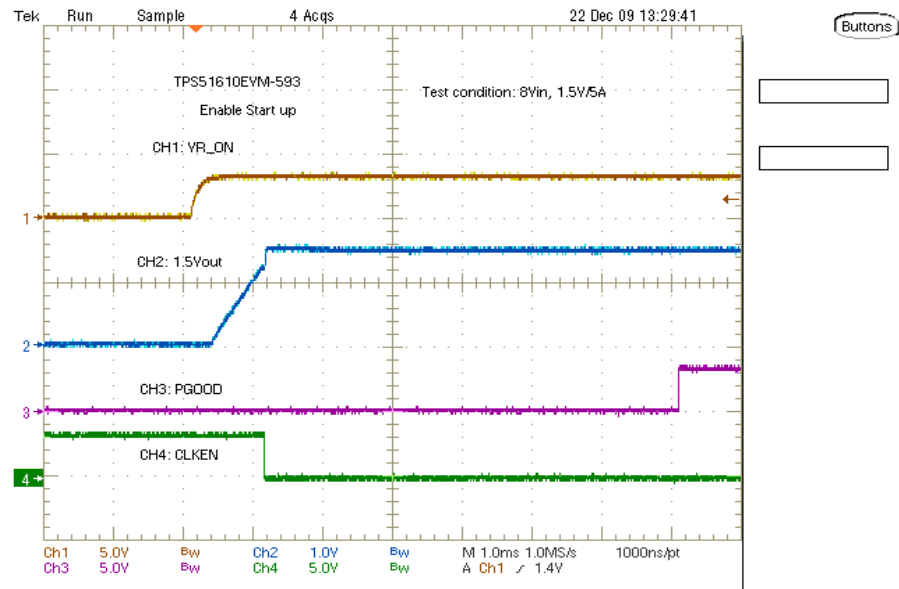
Test condition: 14Vin, 1.5V/5A



**Test condition: 8Vin, 1.5V/0A**

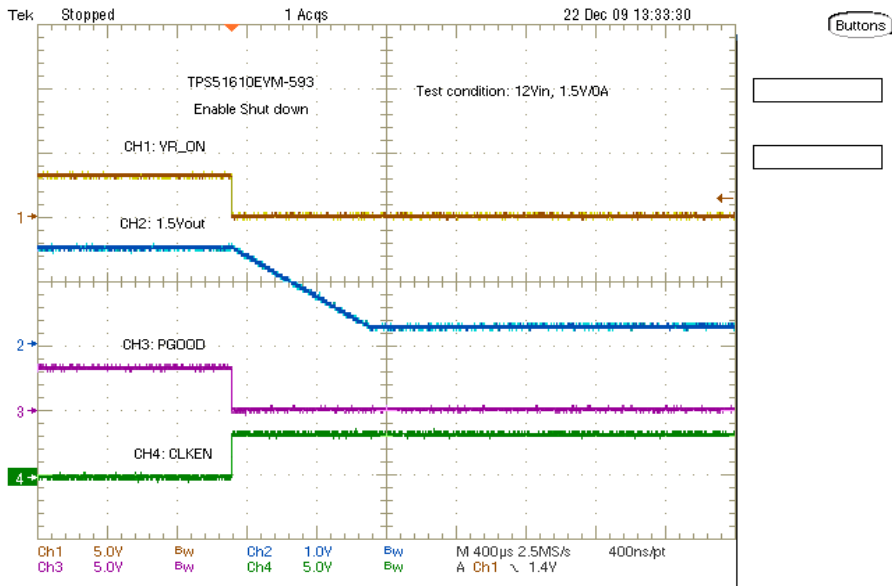


**Test condition: 8Vin, 1.5V/5A**

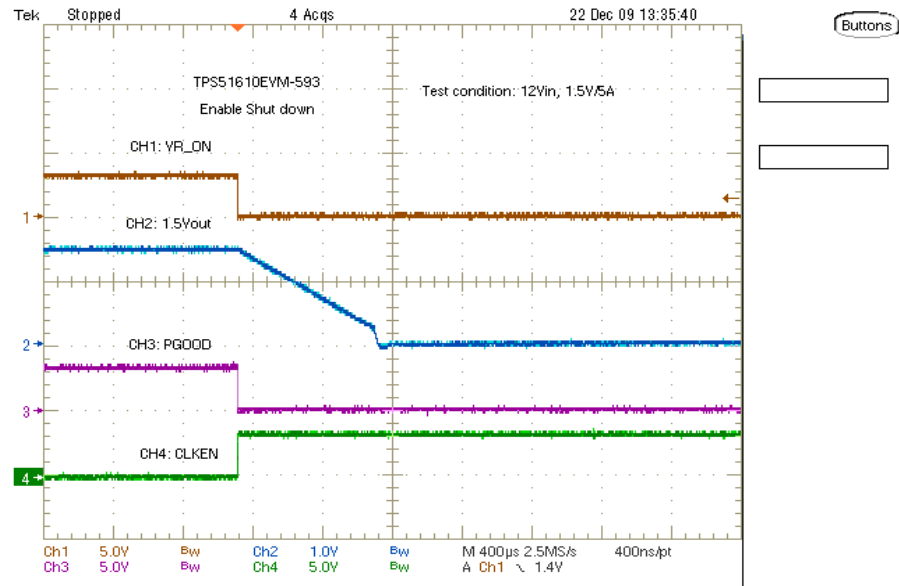


**2. Enable Shutdown**

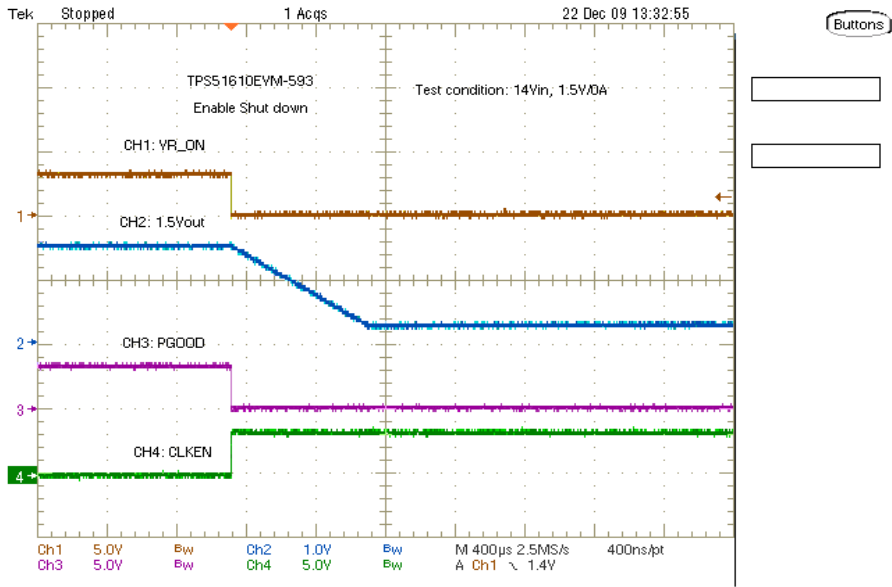
**Test condition: 12Vin, 1.5V/0A**



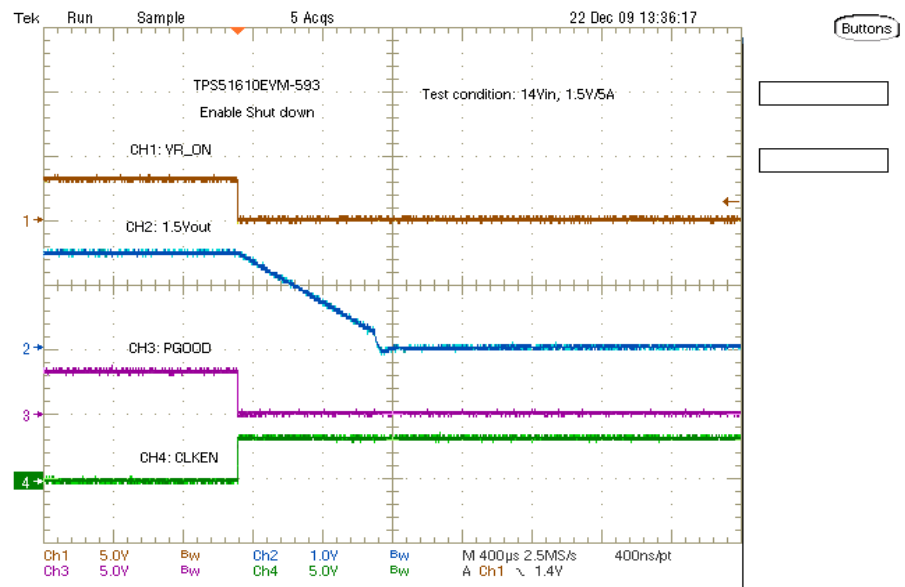
**Test condition: 12Vin, 1.5V/5A**



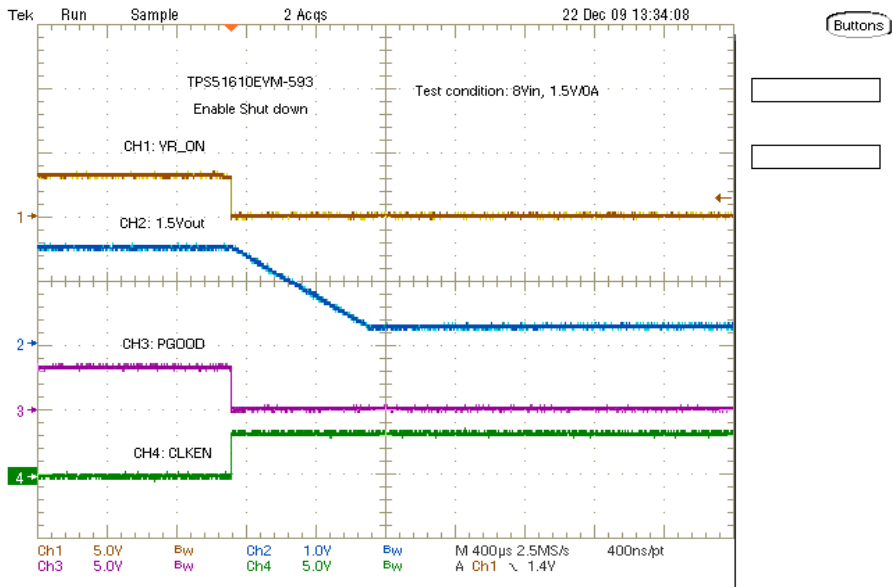
### Test condition: 14Vin, 1.5V/0A



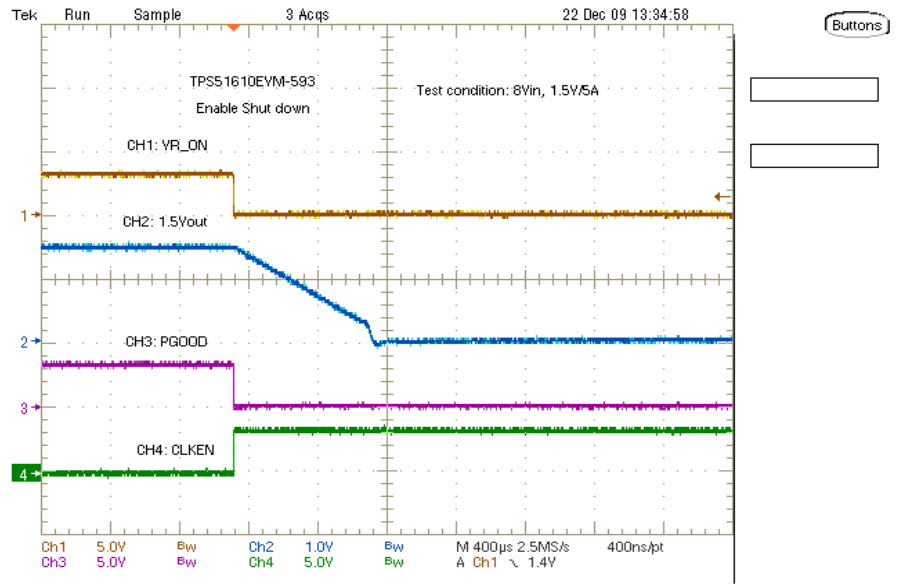
### Test condition: 14Vin, 1.5V/5A



### Test condition: 8Vin, 1.5V/0A

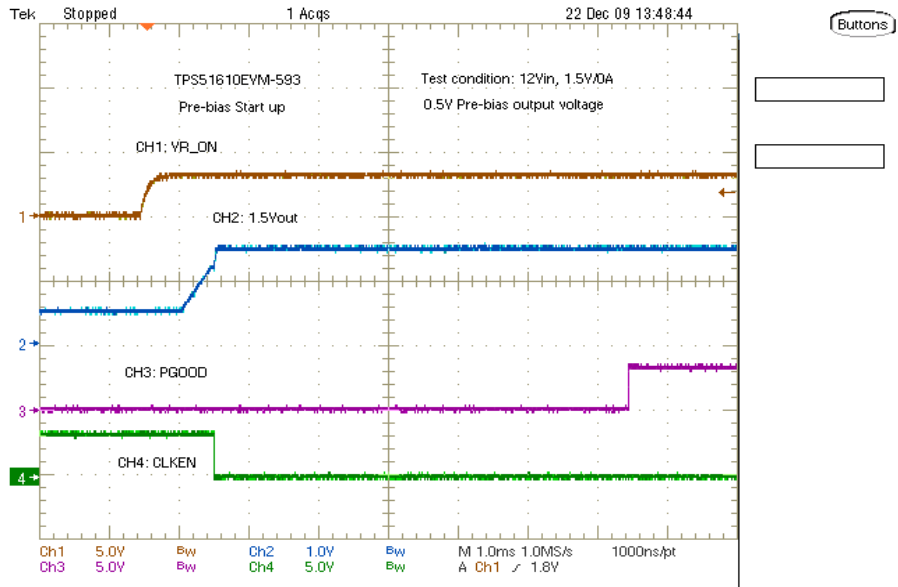


### Test condition: 8Vin, 1.5V/5A

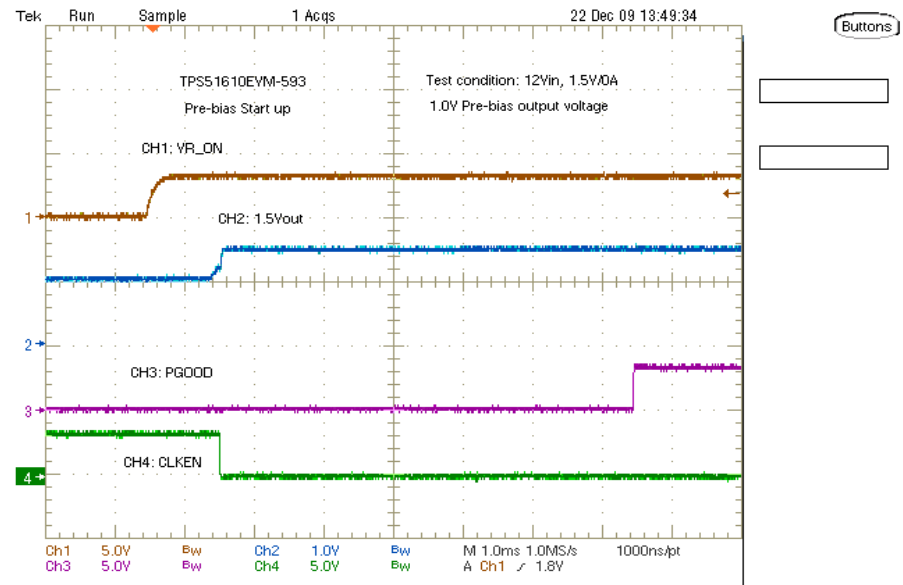


### 3. Pre-bias start up

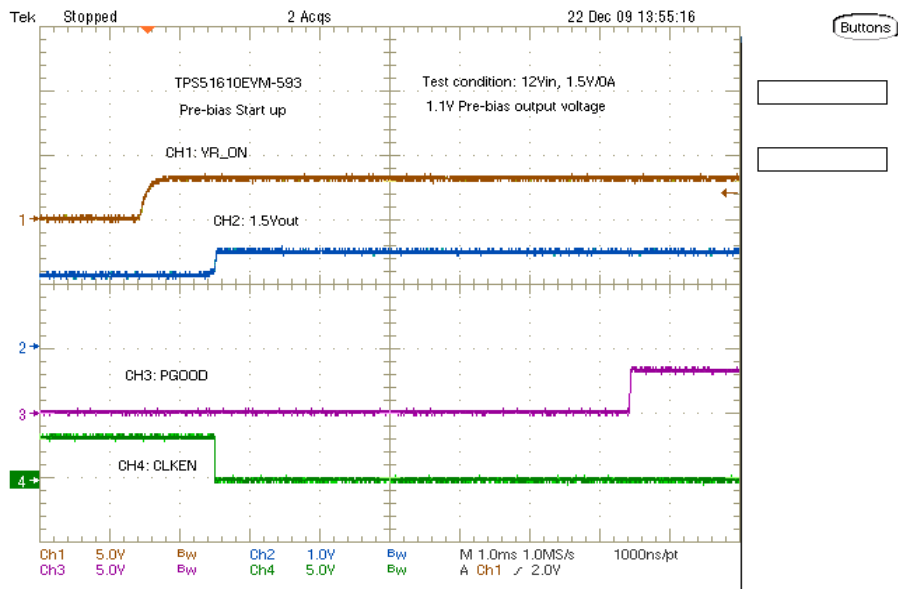
Test condition: 12Vin, 1.5V/0A with pre-bias 0.5V



Test condition: 12Vin, 1.5V/0A with pre-bias 1.0V



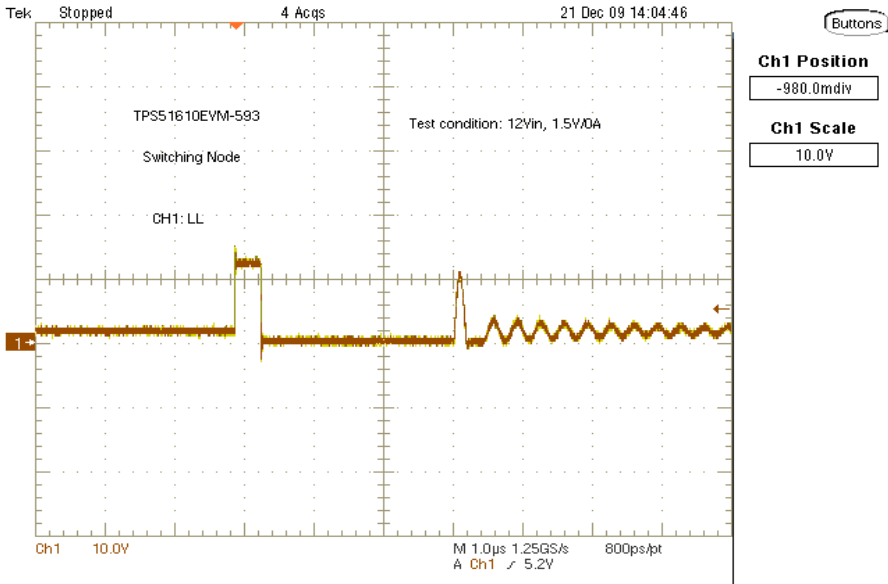
Test condition: 12Vin, 1.5V/0A with pre-bias 1.1V



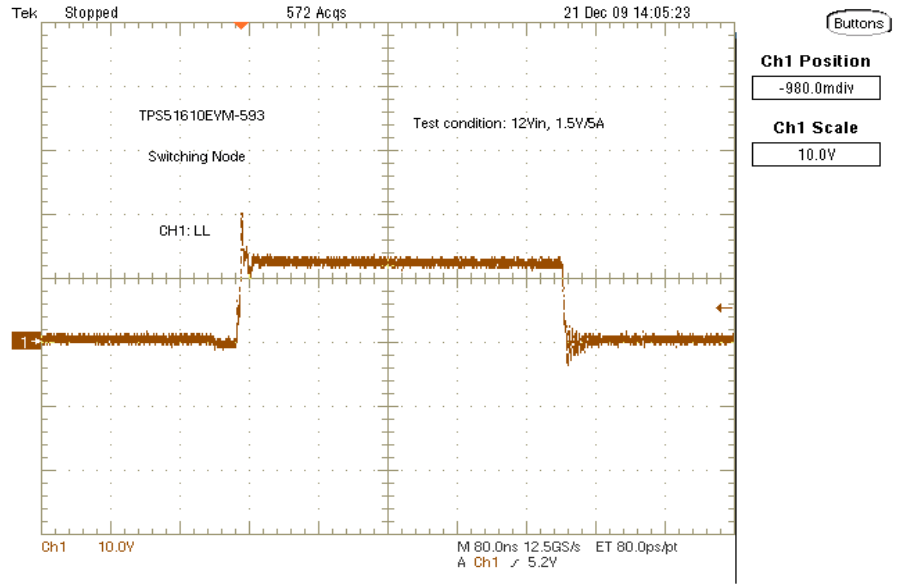
Note: The unit could not start up if the pre-bias voltage is higher than 1.1V

#### 4. Switching node waveform

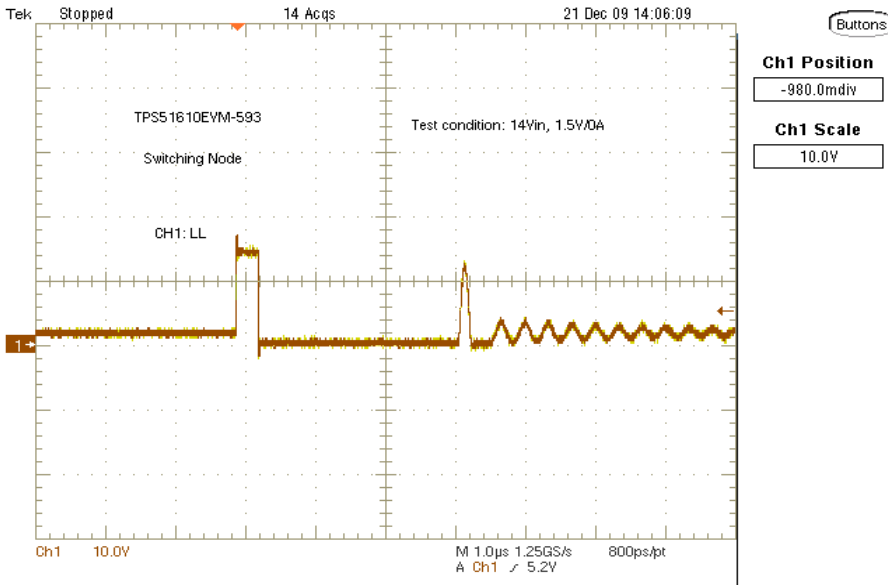
Test condition: 12Vin, 1.5V/0A



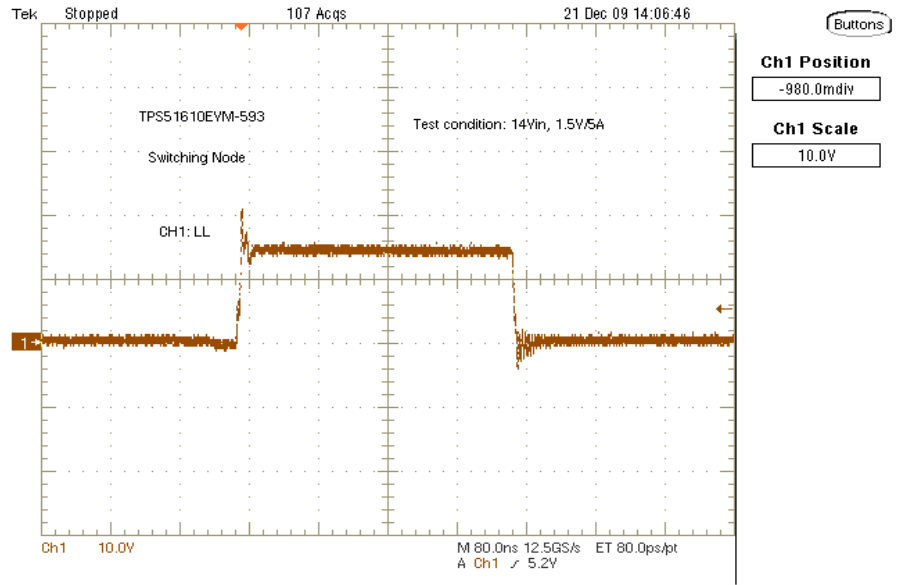
Test condition: 12Vin, 1.5V/5A



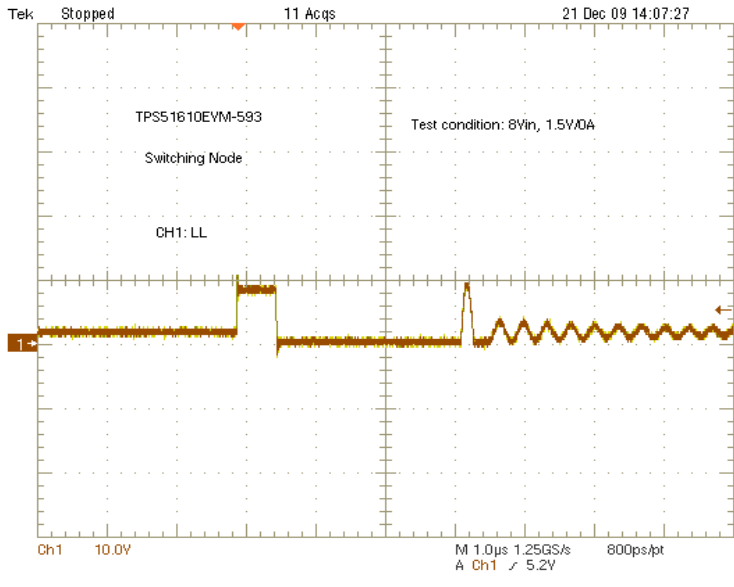
Test condition: 14Vin, 1.5V/0A



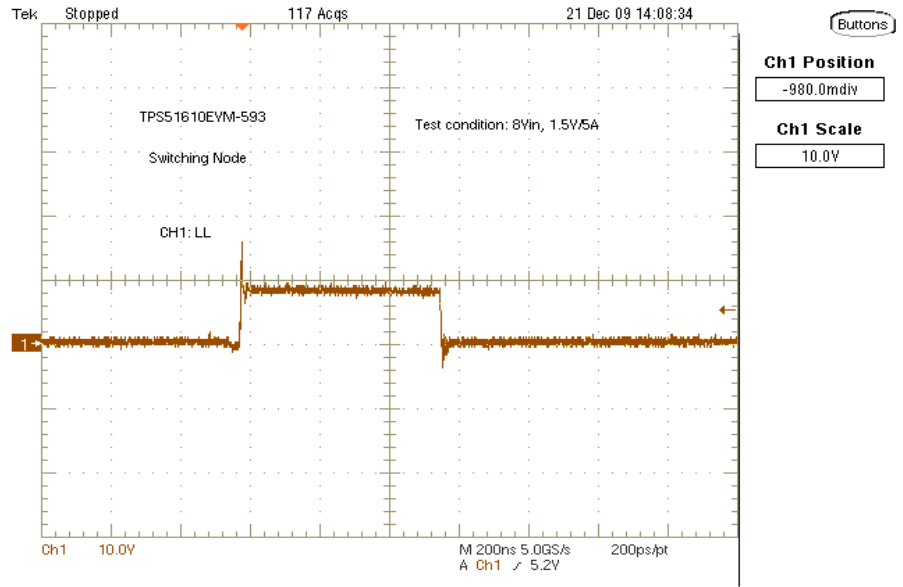
Test condition: 14Vin, 1.5V/5A



### Test condition: 8Vin, 1.5V/0A

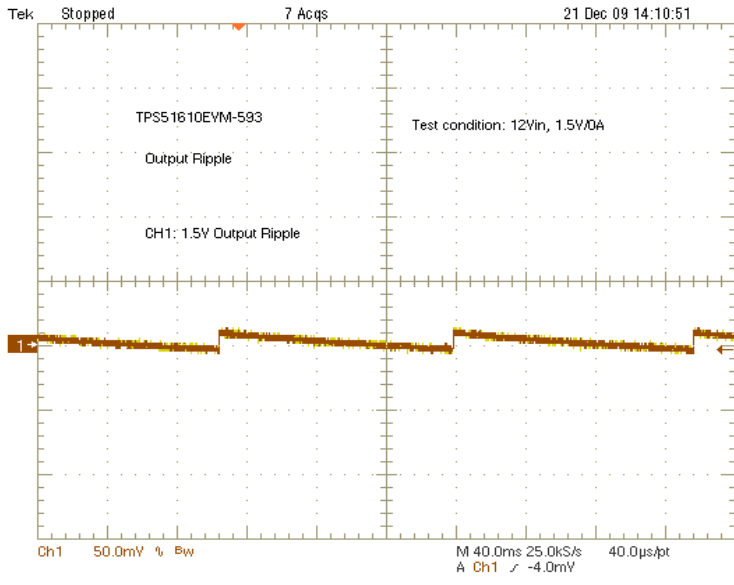


### Test condition: 8Vin, 1.5V/5A

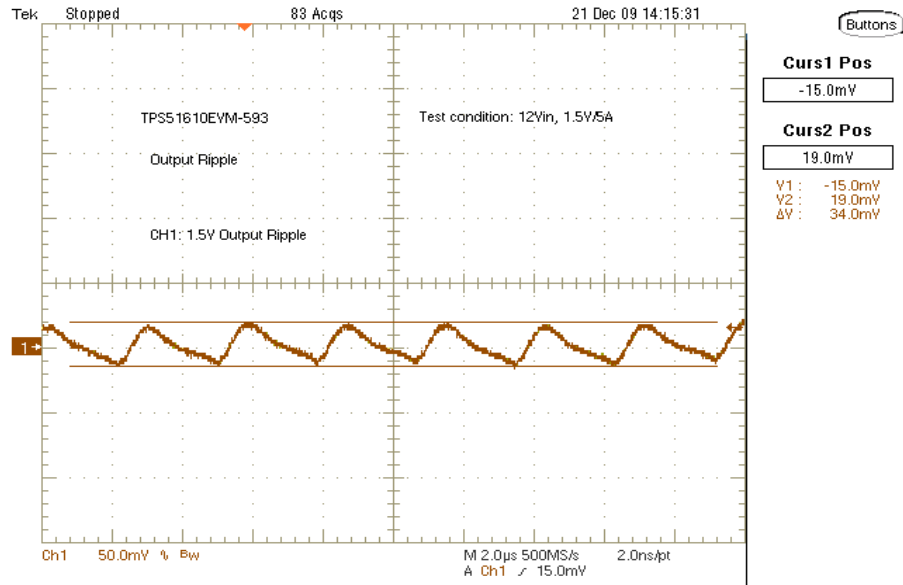


### 5. Output Ripple

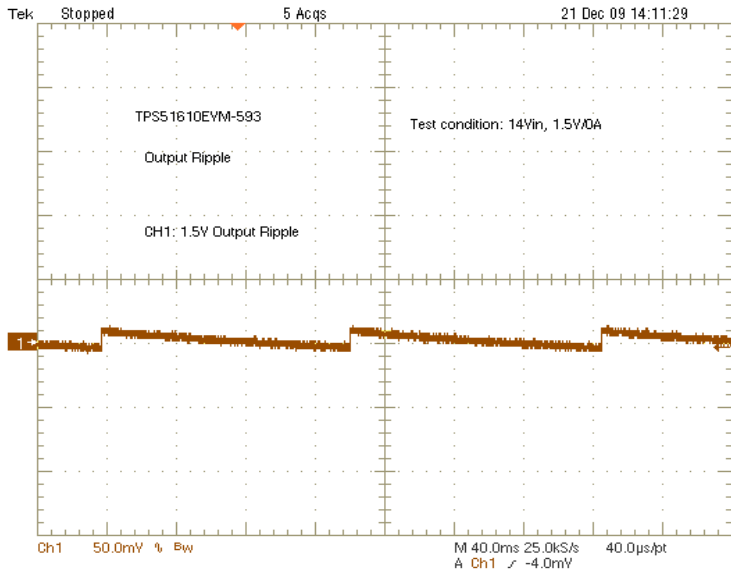
#### Test condition: 12Vin, 1.5V/0A



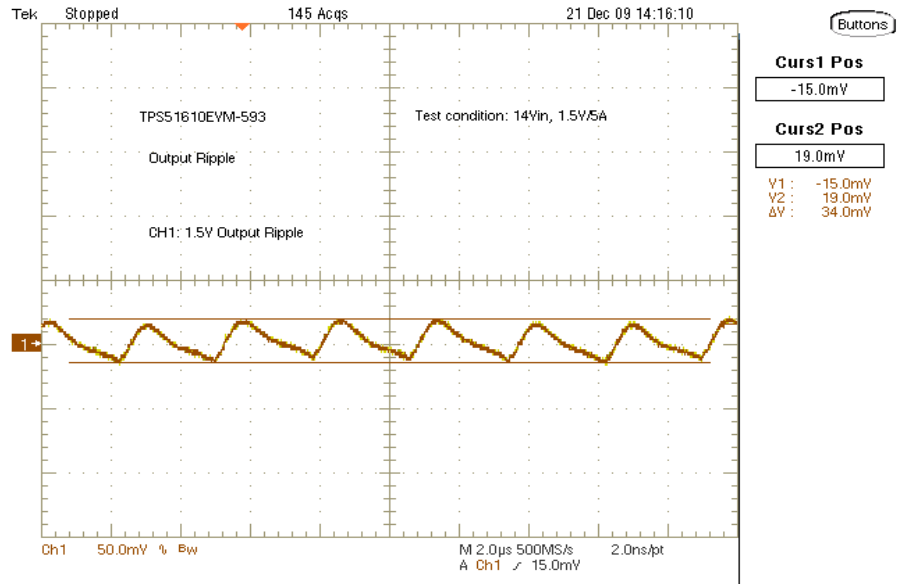
#### Test condition: 12Vin, 1.5V/5A



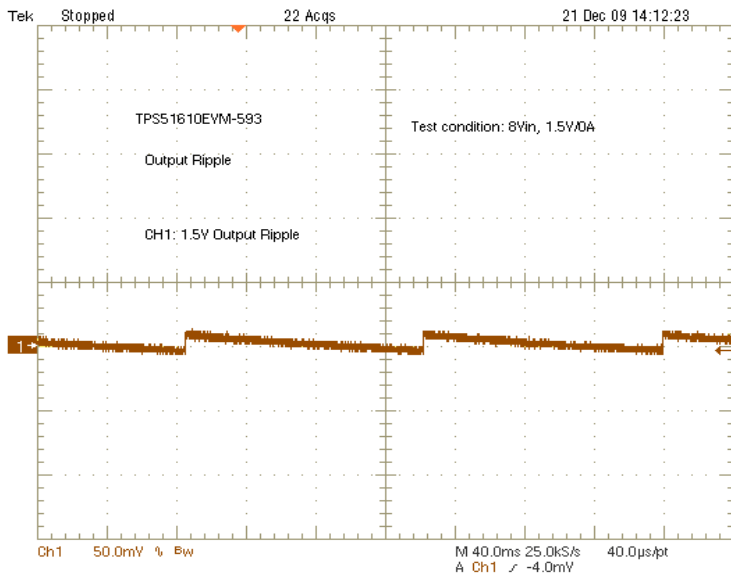
### Test condition: 14Vin, 1.5V/0A



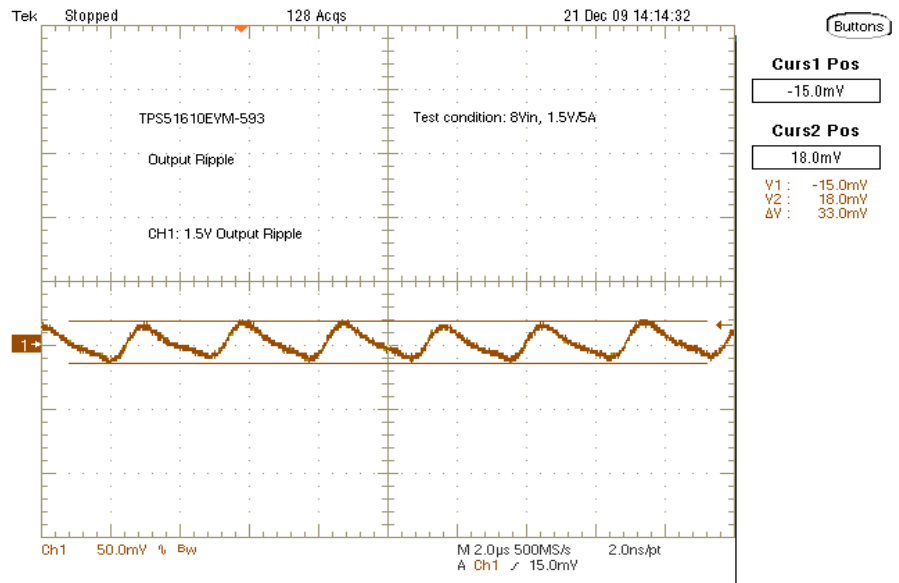
### Test condition: 14Vin, 1.5V/5A



### Test condition: 8Vin, 1.5V/0A

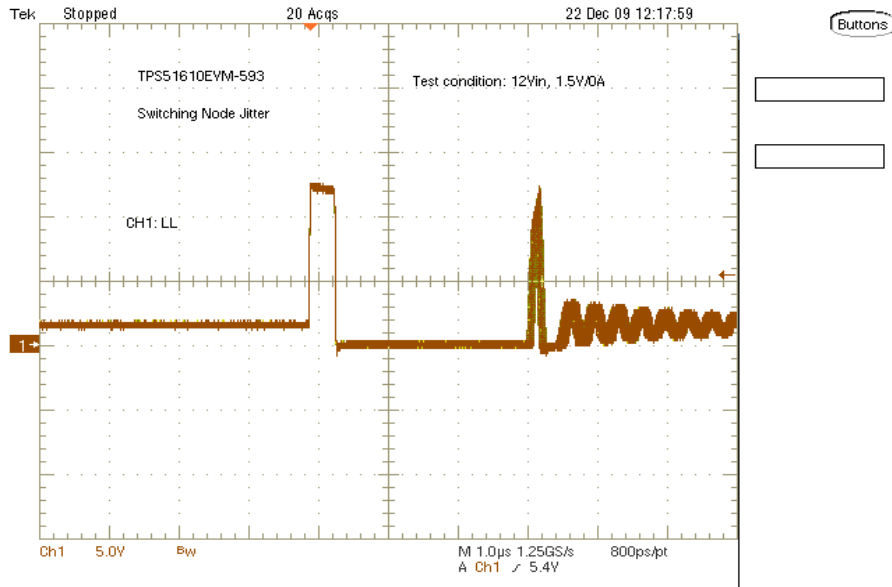


### Test condition: 8Vin, 1.5V/5A

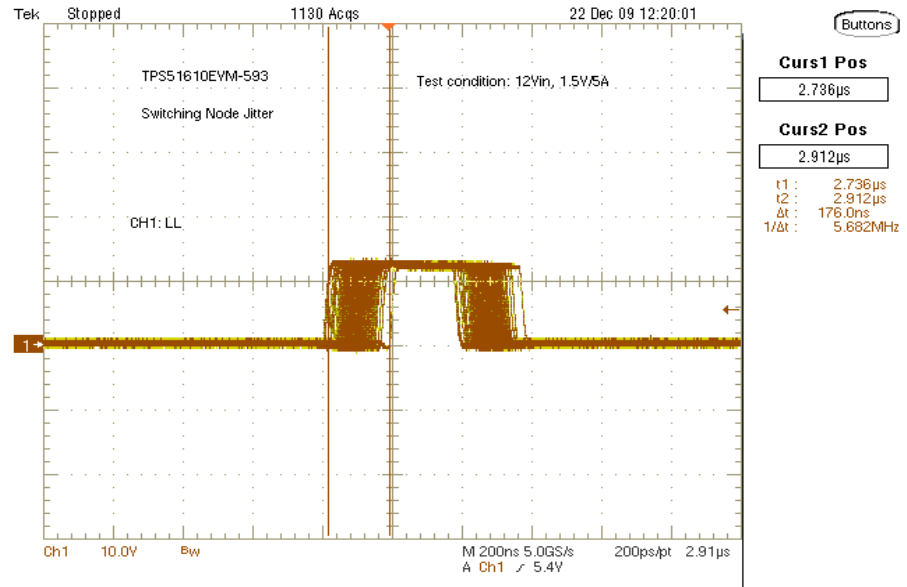


## 6. Switching Node Jitter

Test condition: 12Vin, 1.5V/0A

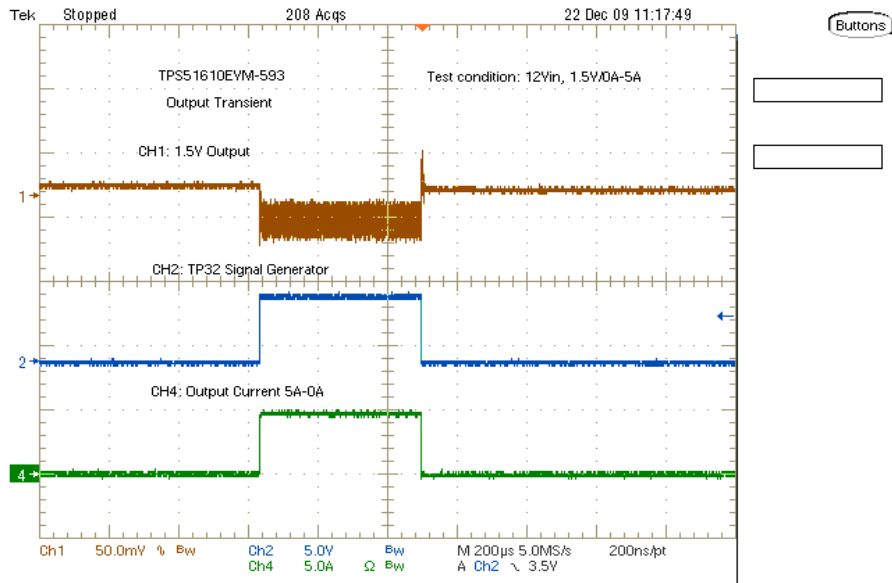


Test condition: 12Vin, 1.5V/5A

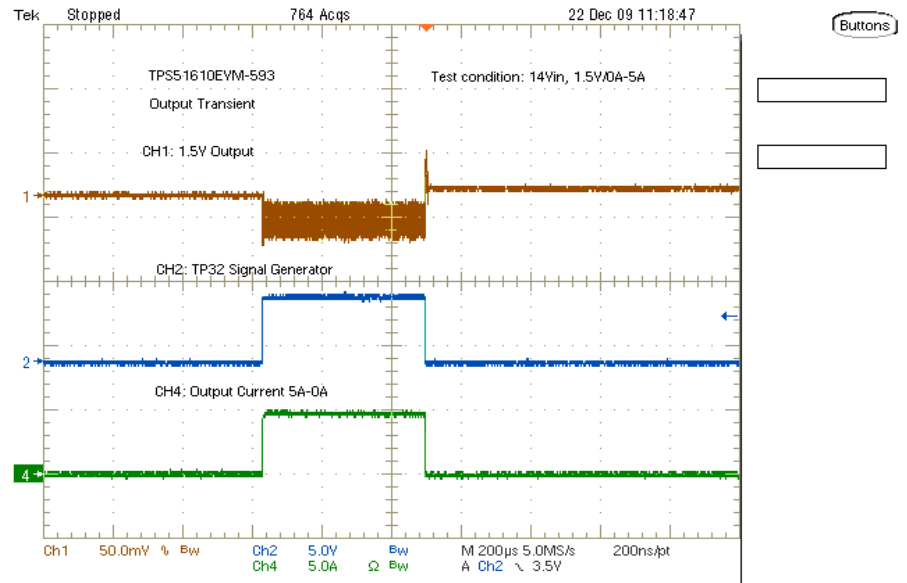


## 7. Transient Response

Test condition: 12Vin, 1.5V/0A-5A

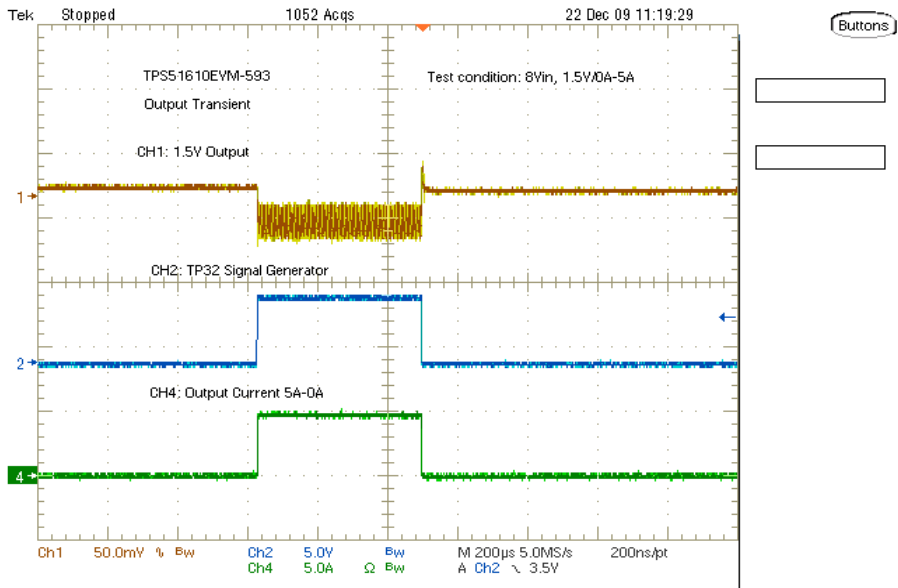


Test condition: 14Vin, 1.5V/0A-5A





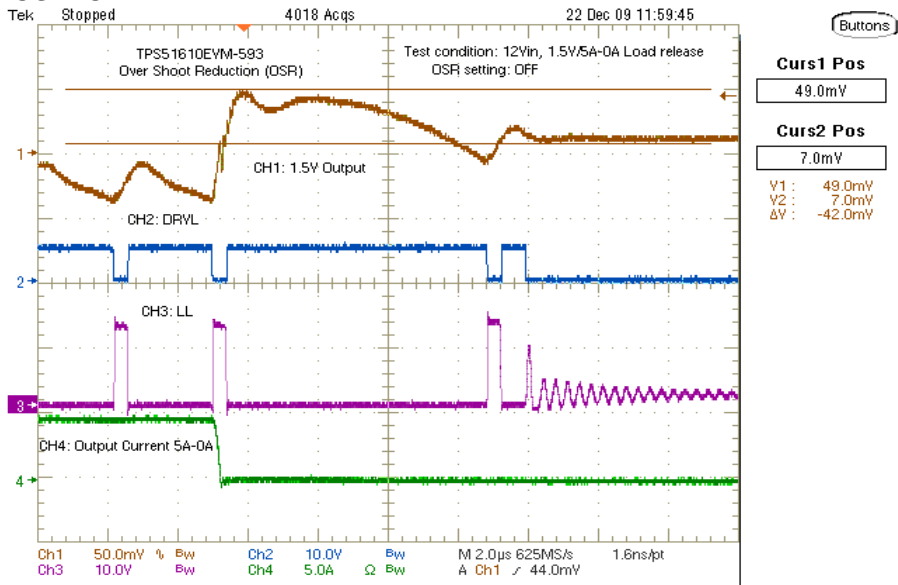
### Test condition: 8Vin, 1.5V/0A-5A



### 8. Over Shoot Reduction(OSR)

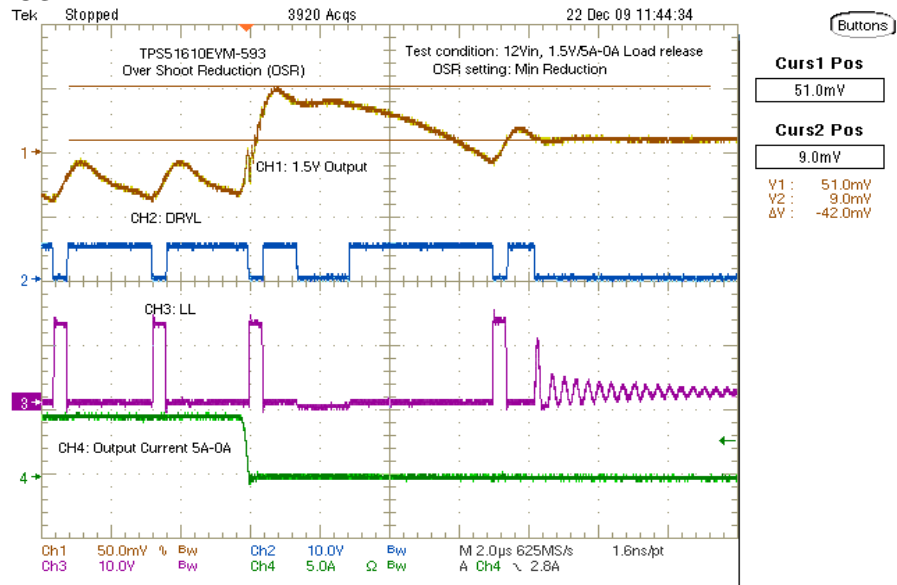
Test condition: 12Vin, 1.5V/0A-5A on board dynamic

OSR=OFF

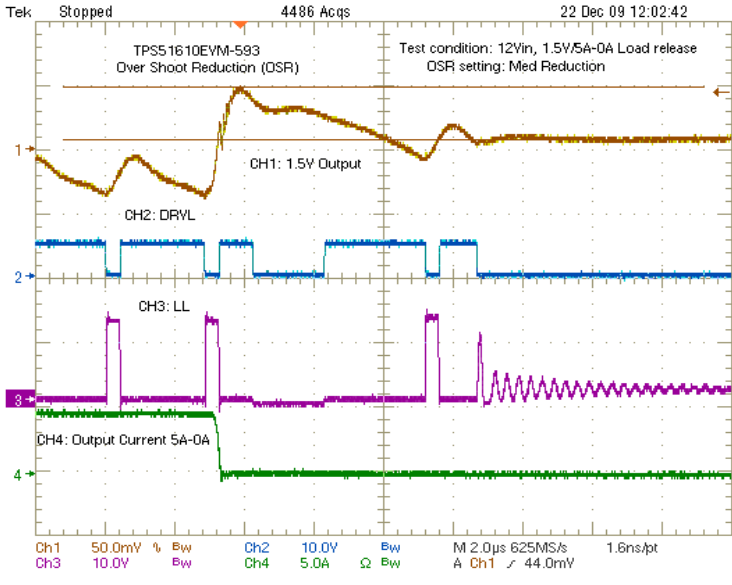


Test condition: 12Vin, 1.5V/0A-5A on board dynamic

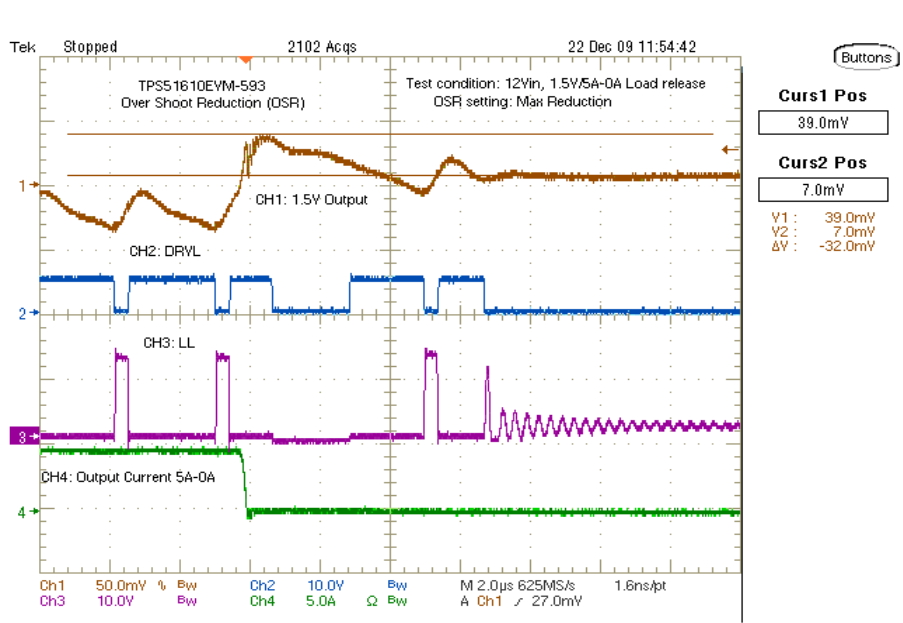
OSR=MIN



**Test condition: 12Vin, 1.5V/0A-5A on board dynamic  
OSR=MED**

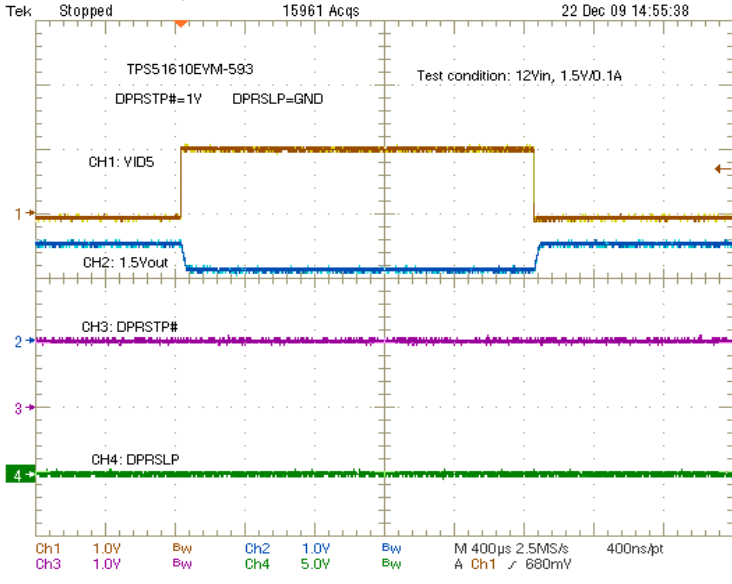


**Test condition: 12Vin, 1.5V/0A-5A on board dynamic  
OSR=MAX**

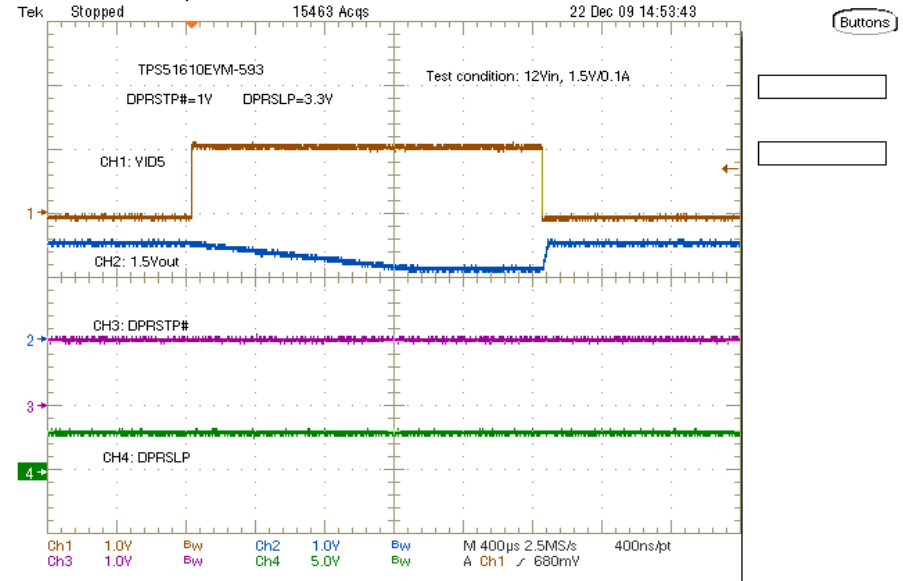


**9. Deep Sleep Mode and Deep Stop Mode**

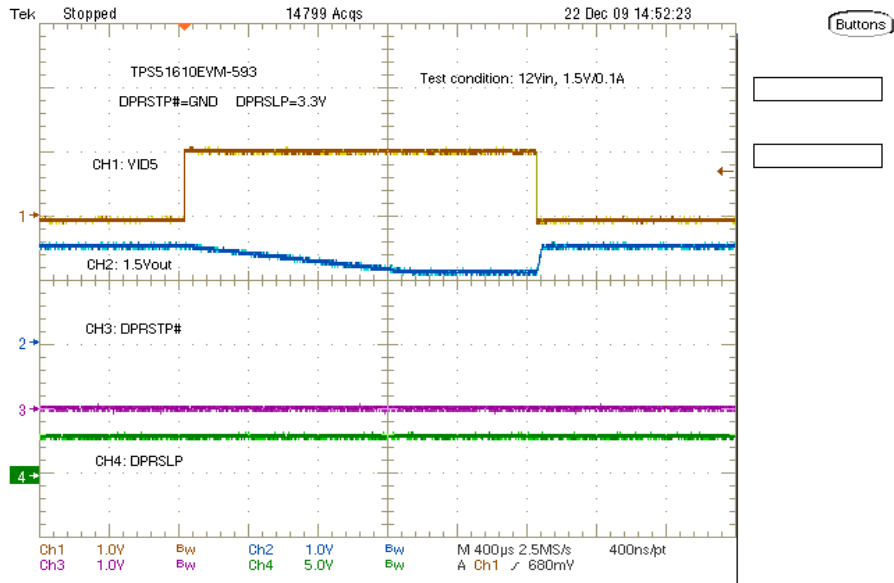
**Test condition: 12Vin, 1.5V/0A VID5 change  
DPRSTP#=1V, DPRSLP=GND**



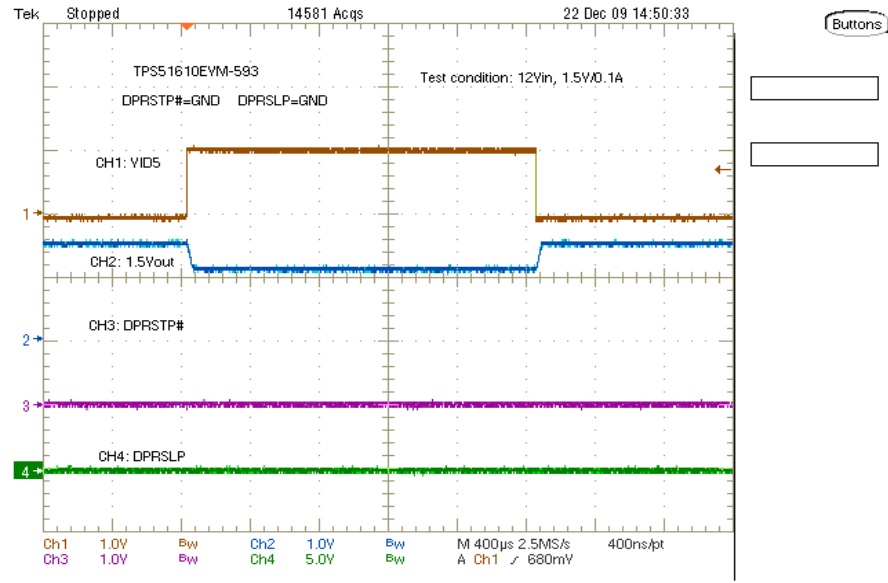
**Test condition: 12Vin, 1.5V/0A VID5 change  
SLP=1V Enable SLP  
DPRSTP#=1V, DPRSLP=3.3V**



Test condition: 12Vin, 1.5V/0A VID5 change  
 DPRSTP#=GND, DPRSLP=3.3V



Test condition: 12Vin, 1.5V/0A VID5 change  
 DPRSTP#=GND, DPRSLP=GND



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